

UCC2897A Peak Current Mode Active-Clamp Forward Converter Small-Signal Modeling Design Consideration

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Power Management/Field Applications

ABSTRACT

UCC2897A is a peak current mode active-clamp controller. This paper discussed the modeling process and loop compensation for UCC2897A. An example has been implemented with the modeling and compensation.

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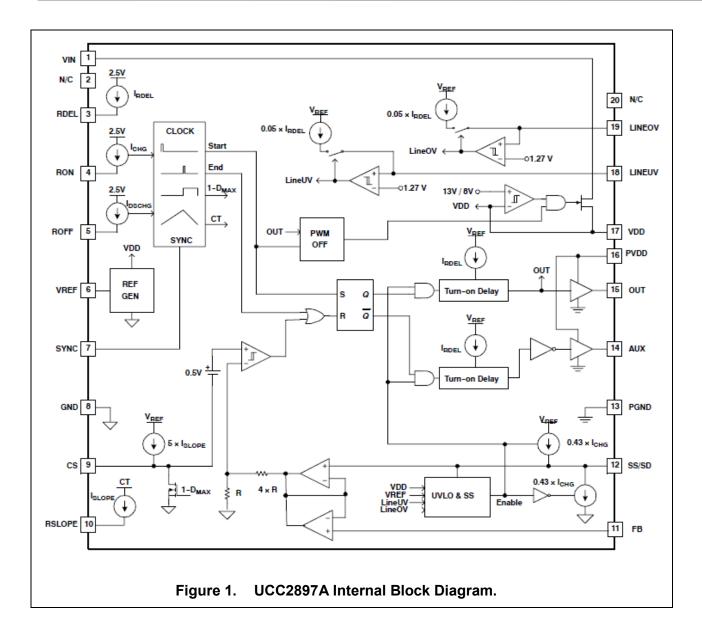
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1 UCC2897A Introduction:

The UCC2897A PWM controller simplifies implementation of the various active clamp/reset and synchronous rectifier switching power topologies. The UCC2897A is peak current-mode, fixed frequency, high performance pulse width modulator. It includes the logic and the drive capability for the P-channel auxiliary switch along with a simple method of programming the critical delays for proper active clamp operation, as showed in Figure.1.





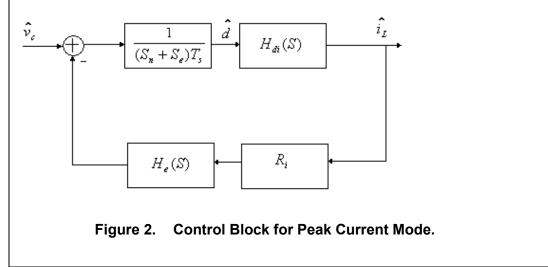
2 Peak Current Mode Small-Signal Circuitry.

A peak current-mode converter, with continuous current mode, introduces a sampling-hold function, as shown in Equations 1 and 2. Figure 2 shows the control block for peak current-mode:

$$H_{e}(s) = \frac{1 - e^{-S \times t_{SW}}}{s \times t_{SW}} \approx \frac{1}{1 + \frac{s}{2/t_{SW}} + \frac{s^{2}}{\pi^{2}/t_{SW}^{2}}};$$
(1)

$$H_{vi}(S) = \frac{I_L(S)}{V_I(S)} \approx \frac{D}{SL_m}$$
(2)





Then, the gain from the error amplifier output to the inductor current can be got:

$$\frac{i_L}{u_c} = H(S) \tag{3}$$

$$H(S) \approx \frac{1}{R_i} \frac{1}{1 + S[\frac{T_s L_m (S_n + S_e)}{V_I R_i} - \frac{T_s}{2}] + S^2 \frac{T_s^2}{\pi^2}}$$
(4)

Define two components as below:

Resistor:
$$R_a = \frac{2L_m}{t_{SW}[\frac{2(S_n + S_e)}{(S_n + S_f)} - 1]};$$
 and Capacitor: $C_a = \frac{t_{SW}^2}{\pi^2 L_m}$ (5)

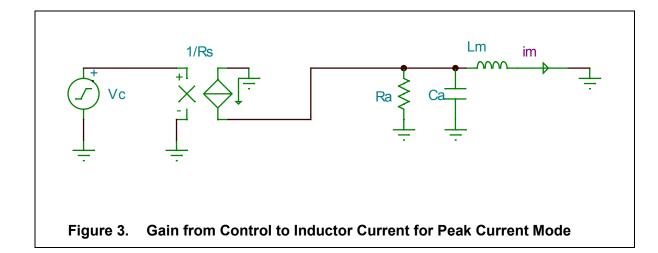
Where:

^

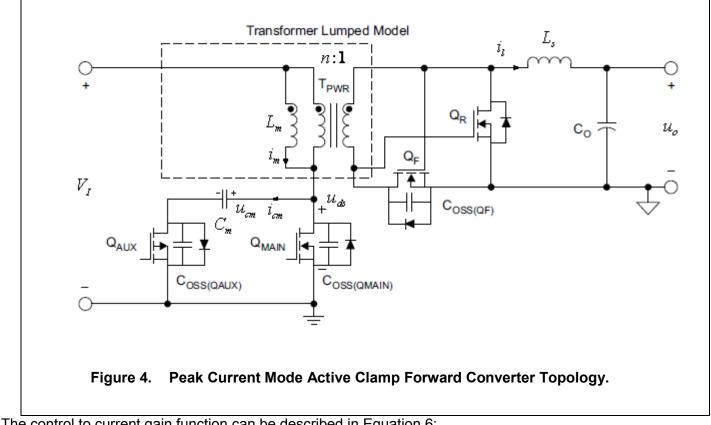
- S_n is the rising rate.
- S_f is the falling rate.
- S_e is the slope compensation rate.

Hereby, the equivalent small signal model from control to inductor current can be obtained as shown in Figure 3.





3 **Active Clamp Peak Current Modeling Analysis:**



The control to current gain function can be described in Equation 6:

$$\frac{\hat{\boldsymbol{u}}_{c}}{R_{s}}\frac{1}{1+\frac{S}{Q\omega_{n}}+\frac{S^{2}}{\omega_{n}^{2}}}=\hat{\boldsymbol{i}}_{m}+\frac{\hat{\boldsymbol{i}}_{l}}{n}$$

With the active-clamping topology,



$$S_n = \left(\frac{V_I}{L_m} + \frac{V_I - nV_o}{n^2 L_s}\right) R_s$$

$$S_f = \left(\frac{DV_I}{(1 - D)L_m} + \frac{V_o}{nL_s}\right) R_s$$
(7)

n is the transformer turn ratio between primary and secondary side windings.

Therefore,
$$Q = \frac{1}{\pi (\frac{S_n + S_e}{S_n + S_f} - 0.5)}; \ \omega_n = \frac{\pi}{T_{sw}}$$
 (8)

The clamping circuitry modeling:

$$< i_{cm} >= (1 - \langle d \rangle) < i_{m} >; < i_{cm} >= I_{cm} + \dot{i}_{cm}; < d >= D + \dot{d}; < i_{m} >= I_{m} + \dot{i}_{m}$$
(9)

Where:

- <> means the cycle average function.
- ^ means the perturbation element.
- d is the duty cycle of the main switch;

Considering the magnetic operating in symmetrically, the average current I_c and I_m are zero.

$$\dot{i_{cm}} = (1-D)\dot{i_m}$$
(10)

The Vds of MOSFET modeling:

$$\hat{u}_{ds} = -\frac{D}{(1-D)} V_{in} \dot{d} + (1-D) \hat{u}_{cm}$$
(11)

And:
$$\hat{u}_{ds}^{*} = -SL_{m}\hat{i}_{m}^{*}; \quad \hat{u}_{cm}^{*} = -\frac{1}{SC_{m}}\hat{i}_{cm}^{*}$$
 (12)

esult,
$$V_{in} \dot{d} = [S \frac{(1-D)L_m}{D} + \frac{(1-D)^3}{SDC_m}]\dot{l_m}$$
 (13)

As re

$$L_{e} = \frac{(1-D)}{D} L_{m}; C_{e} = \frac{D}{(1-D)^{3}} C_{m}$$
(14)

Define:

5

SLUA702

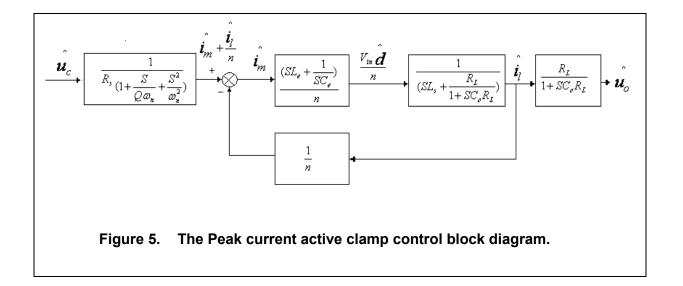
 \wedge

^

Then:
$$\frac{V_{in} \vec{d}}{n} = \frac{(SL_e + \frac{1}{SC_e})\hat{i}_m}{n};$$
 (15)
And: $\hat{i}_l = \frac{1}{(SL_s + \frac{R_L}{1 + SC_aR_L})} \frac{V_{in} \vec{d}}{n}$ (16)

S

RUMENTS



$$G_{co}(S) = \frac{\mathcal{U}_{o}}{\mathcal{U}_{c}} = \frac{R_{L}(1 + S^{2}L_{e}C_{e})}{R_{s}(1 + \frac{S}{Q\omega_{n}} + \frac{S^{2}}{\omega_{n}^{2}})[S^{3}(L_{e} + n^{2}L_{s})C_{o}C_{e}R_{L} + S^{2}(L_{e} + n^{2}L_{s})C_{e} + S(C_{o} + n^{2}C_{e})R_{L} + 1]}$$
(17)

With $C_o >> n^2 C_e$, this formula can be simplified as in Equation 18:

$$G_{co}(S) = \frac{\mathcal{U}_{o}}{\mathcal{U}_{c}} \approx \frac{R_{L}(1 + S^{2}L_{e}C_{e})}{R_{s}(1 + \frac{S}{Q\omega_{n}} + \frac{S^{2}}{\omega_{n}^{2}})[S^{2}(L_{e} + n^{2}L_{s})C_{e} + 1](SC_{o}R_{L} + 1)}$$
(18)

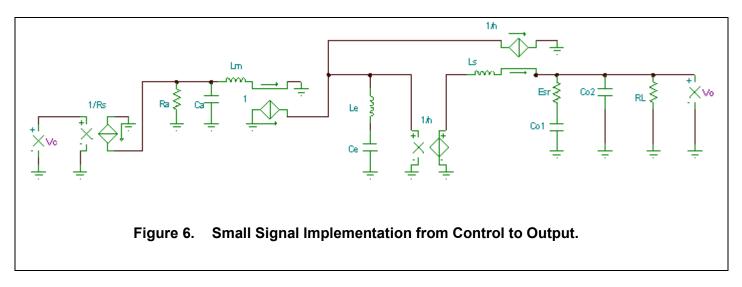
The above Equation (18) introduced dual zeros and dual poles.

$$f_{z} = \frac{1}{2\pi\sqrt{L_{e}C_{e}}} = \frac{(1-D)}{2\pi\sqrt{L_{m}C_{m}}}; f_{p} = \frac{1}{2\pi\sqrt{(L_{e}+n^{2}L_{s})C_{e}}} = \frac{(1-D)}{2\pi\sqrt{(L_{m}+\frac{D}{1-D}n^{2}L_{s})C_{m}}}$$
(19)

Generally, to avoid the instability, the closed-loop crossover frequency "fc", should be far less than half of the pole frequency "fp". Here, "fp" should be the value with the maximum limited duty cycle "D".

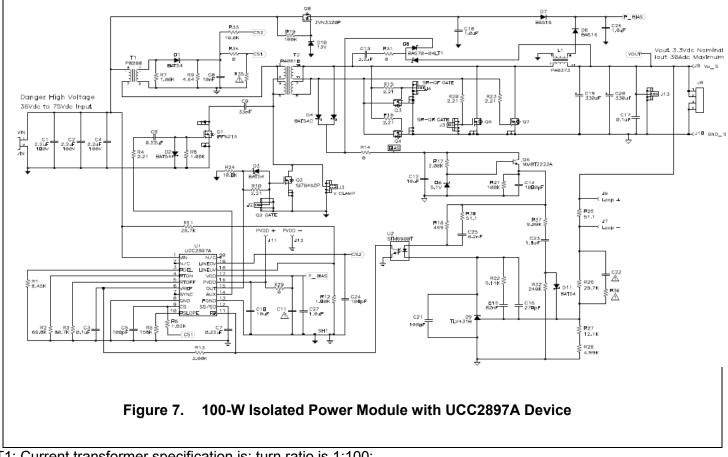


Figure 6 shows a small-signal circuitry implementation:



A Design Example: 4

The design schematic (see Figure 7) and electric specification follow.





T2: Transformer specification is: PA0810NL; turn ratio is 6:1; Lm is 345 µH.

L1 inductor specification is: PA0373; 2.1 µH;

 $Vin = 72V; Vout = 3.3V; I_{out} = 30A$

Based on the schematic design in Figure.7, and the small signal analysis, we can get the overall simulation model as Figure.8:

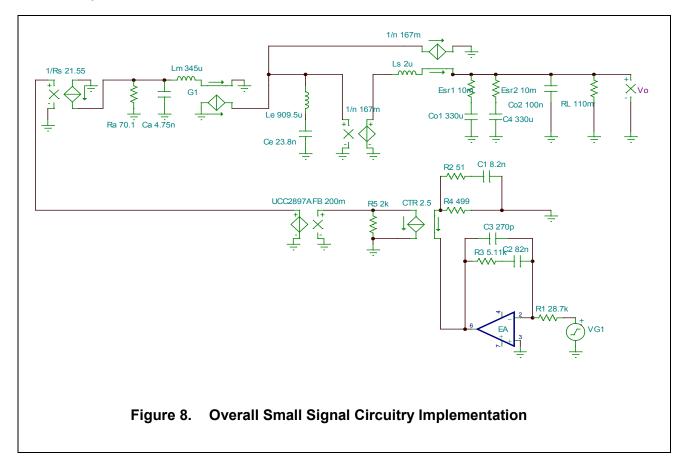


Figure 9 shows the simulation results.



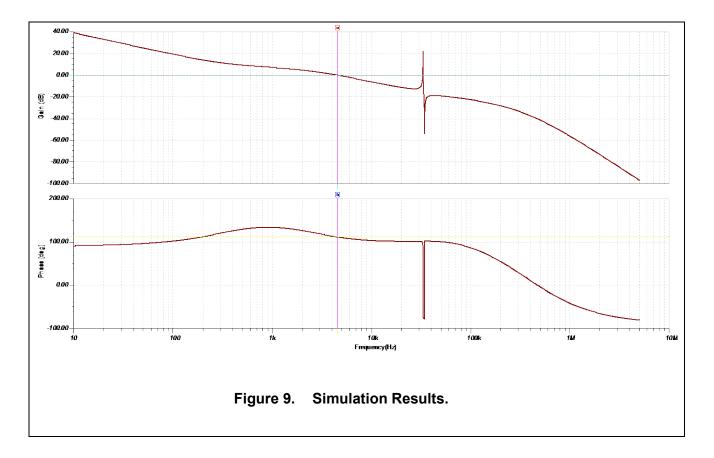


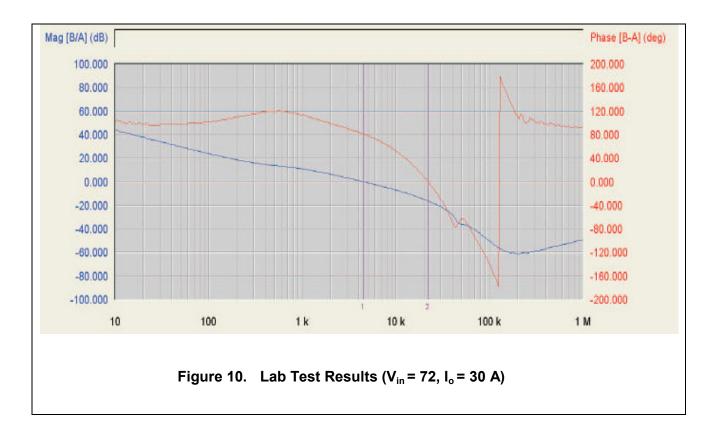
Figure.9 showed the cross-over frequency is 4.5 kHz, and phase margin is 111 degrees.

By lab test results, we can get the results as shown in Figure.10.

The test results showed cross-over frequency is 4.5 kHz and phase margin is 80 degrees.

Comparing the simulation and test results, they matched fully.





5 Conclusion:

The analysis shows the modeling and compensation is effective. The analysis revealed the zero and poles of the peak current mode control active-clamp forward converter, which is critical for the design of the active-clamp converter.

Reference:

- 1. Texas instruments, SLUS829D, UCC2897A datasheet.
- 2. Texas instruments, SLUU357, UCC2897A EVM User's Guide.

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